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# **ABSTRACT**

A wafer-scale assembly apparatus for integrated circuits and a method for forming the wafer-scale assembly are disclosed. A semiconductor wafer including a plurality of circuits is provided with a plurality of metal contact pads as electrical entry and exit ports. A first wafer-scale patterned polymer film carrying solder balls for each of the contact pads on the wafer is positioned opposite the wafer, and the wafer and the film are aligned. The film is brought into contact with the wafer. Radiant energy in the near infrared spectrum is applied to the backside of the wafer, heating the wafer uniformly and rapidly without moving the semiconductor wafer. Thermal energy is transferred through the wafer to the surface of the wafer and into the solder balls, which reflow onto the contact pads, while the thermal stretching of the polymer film is mechanically compensated. The uniformity of the height of the liquid solder balls is controlled either by mechanical stoppers or by the precision linear motion of motors. After cooling, the solder balls solidify and the first polymer film is removed. The process is repeated for assembling sequentially a wafer-scale patterned interposer overlying all of the solder balls and the wafer and contacting each solder ball with a soldered joint, and a second wafer-scale patterned film carrying solder balls contacting the interposer. In each process, the wafer is heated uniformly and rapidly and without moving it, the alignment is maintained during heating by mechanically compensating for the thermal stretching of the polymer film, and the uniformity of the height of the liquid solder balls is controlled by mechanical stoppers or position closed-loop linear actuators. The second film is removed after cooling. Other embodiments are also disclosed.

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